

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	870	(((((chip or die or semiconductor or ic or (integrated adj circuit)) and (sockets or socket or (cantilever near5 pin) or (passage or passageway) near5 pin))) and ("257"/\$6.ccls.)) and (force)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/23 14:57
L2	219	(((((257/692.ccls. or 257/697.ccls. or 257/696.ccls. or 257/693.ccls. or 257/669.ccls. or 257/674.ccls. or 257/672.ccls. or 257/673.ccls. or 257/676.ccls. or 257/690.ccls. or 257/634.ccls. or 257/773.ccls. or 257/774.ccls. or 257/698.ccls.) and (semiconductor or die or chip or ic or (integrated adj circuit))) and (lead or electrode or wire or contact)) and (socket or via or (through adj hole) or slit or slot or opening)) and (insert)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/23 14:58
S1	10063	(chip or die or semiconductor) and (grid adj array)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/11/06 17:08
S2	649	((chip or die or semiconductor) and (grid adj array)) and sockets	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/23 12:57
S3	1	("0055291").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2002/11/06 15:31
S4	0	("200200055291").PN.	US-PGPUB; USOCR	OR	OFF	2002/11/06 15:31
S5	0	"200200055291"	US-PGPUB	OR	OFF	2002/11/06 15:32
S6	1	("6316830").PN.	USPAT; USOCR	OR	OFF	2002/11/06 15:33
S7	1	("6372527").PN.	USPAT; USOCR	OR	OFF	2002/11/06 15:33
S8	1	("6054756").PN.	USPAT; USOCR	OR	OFF	2002/11/06 15:33
S9	1	("4943846").PN.	USPAT; USOCR	OR	OFF	2002/11/06 15:33
S10	1	("4953060").PN.	USPAT; USOCR	OR	OFF	2002/11/06 15:33
S11	619	257/698.ccls.	USPAT	OR	OFF	2004/08/25 12:42
S12	740	257/692.ccls.	USPAT	OR	OFF	2002/11/06 17:09

S13	280	257/697.ccls.	USPAT	OR	OFF	2002/11/06 17:09
S14	328	257/696.ccls.	USPAT	OR	OFF	2002/11/06 17:09
S15	532	257/693.ccls.	USPAT	OR	OFF	2002/11/06 17:09
S16	298	257/669.ccls.	USPAT	OR	OFF	2002/11/06 17:09
S17	175	257/674.ccls.	USPAT	OR	OFF	2002/11/06 17:09
S18	202	257/672.ccls.	USPAT	OR	OFF	2002/11/06 17:09
S19	852	257/676.ccls.	USPAT	OR	OFF	2002/11/06 17:09
S20	538	257/690.ccls.	USPAT	OR	OFF	2002/11/06 17:10
S21	75	257/634.ccls.	USPAT	OR	OFF	2002/11/06 17:10
S22	204	257/673.ccls.	USPAT	OR	OFF	2002/11/06 17:10
S23	471	257/734.ccls.	USPAT	OR	OFF	2002/11/06 17:10
S24	1158	257/773.ccls.	USPAT	OR	OFF	2002/11/06 17:10
S25	983	257/774.ccls.	USPAT	OR	OFF	2002/11/06 17:10
S26	64	361/731.ccls.	USPAT	OR	OFF	2002/11/06 17:11
S27	73	361/723.ccls.	USPAT	OR	OFF	2002/11/06 17:11
S28	83	361/722.ccls.	USPAT	OR	OFF	2002/11/06 17:11
S29	658	361/719.ccls.	USPAT	OR	OFF	2002/11/06 17:11
S30	153	361/637.ccls.	USPAT	OR	OFF	2002/11/06 17:11
S31	178	361/768.ccls.	USPAT	OR	OFF	2002/11/06 17:11
S32	51	361/640.ccls.	USPAT	OR	OFF	2002/11/06 17:11
S33	471	361/785.ccls.	USPAT	OR	OFF	2002/11/06 17:12
S34	151	361/633.ccls.	USPAT	OR	OFF	2002/11/06 17:30
S35	77	361/636.ccls.	USPAT	OR	OFF	2002/11/06 17:49
S36	1	("4700214").PN.	USPAT; USOCR	OR	OFF	2002/11/13 15:13
S37	43818	((chip or die or semiconductor or ic or (integrated adj circuit)) and (sockets or socket or (cantilever near5 pin) or (passage or passageway) near5 pin))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/23 13:00
S38	2367	((((chip or die or semiconductor or ic or (integrated adj circuit)) and (sockets or socket or (cantilever near5 pin) or (passage or passageway) near5 pin))) and ("257"/\$6.ccls.))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/23 14:58
S39	810	(((((chip or die or semiconductor or ic or (integrated adj circuit)) and (sockets or socket or (cantilever near5 pin) or (passage or passageway) near5 pin))) and ("257"/\$6.ccls.)) and (force))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/23 14:57

S40	1557	(((((chip or die or semiconductor or ic or (integrated adj circuit)) and (sockets or socket or (cantilever near5 pin) or (passage or passageway) near5 pin))) and ("257"/\$6.ccls.)) not (((((chip or die or semiconductor or ic or (integrated adj circuit)) and (sockets or socket or (cantilever near5 pin) or (passage or passageway) near5 pin))) and ("257"/\$6.ccls.)) and (force))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/23 15:00
S41	828	257/698.ccls.	USPAT	OR	OFF	2004/08/25 12:45
S42	0	257/6928.ccls.	USPAT	OR	OFF	2004/08/25 12:43
S43	1597	257/692.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:43
S44	736	257/697.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:43
S45	926	257/696.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:43
S46	1282	257/693.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:43
S47	689	257/669.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:43
S48	330	257/674.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:43
S49	325	257/672.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:44

S50	423	257/673.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:44
S51	2044	257/676.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:44
S52	1517	257/690.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:44
S53	135	257/634.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:44
S54	2012	257/773.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:44
S55	1948	257/774.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:44
S56	1249	257/698.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:45
S57	12130	257/692.ccls. or 257/697.ccls. or 257/696.ccls. or 257/693.ccls. or 257/669.ccls. or 257/674.ccls. or 257/672.ccls. or 257/673.ccls. or 257/676.ccls. or 257/690.ccls. or 257/634.ccls. or 257/773.ccls. or 257/774.ccls. or 257/698.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:46
S58	11183	(257/692.ccls. or 257/697.ccls. or 257/696.ccls. or 257/693.ccls. or 257/669.ccls. or 257/674.ccls. or 257/672.ccls. or 257/673.ccls. or 257/676.ccls. or 257/690.ccls. or 257/634.ccls. or 257/773.ccls. or 257/774.ccls. or 257/698.ccls.) and (semiconductor or die or chip or ic or (integrated adj circuit))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:52

S59	9793	((257/692.ccls. or 257/697.ccls. or 257/696.ccls. or 257/693.ccls. or 257/669.ccls. or 257/674.ccls. or 257/672.ccls. or 257/673.ccls. or 257/676.ccls. or 257/690.ccls. or 257/634.ccls. or 257/773.ccls. or 257/774.ccls. or 257/698.ccls.) and (semiconductor or die or chip or ic or (integrated adj circuit))) and (lead or electrode or wire or contact)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:53
S60	5605	((257/692.ccls. or 257/697.ccls. or 257/696.ccls. or 257/693.ccls. or 257/669.ccls. or 257/674.ccls. or 257/672.ccls. or 257/673.ccls. or 257/676.ccls. or 257/690.ccls. or 257/634.ccls. or 257/773.ccls. or 257/774.ccls. or 257/698.ccls.) and (semiconductor or die or chip or ic or (integrated adj circuit))) and (lead or electrode or wire or contact)) and (socket or via or (through adj hole) or slit or slot or opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/08/25 12:54
S61	207	((257/692.ccls. or 257/697.ccls. or 257/696.ccls. or 257/693.ccls. or 257/669.ccls. or 257/674.ccls. or 257/672.ccls. or 257/673.ccls. or 257/676.ccls. or 257/690.ccls. or 257/634.ccls. or 257/773.ccls. or 257/774.ccls. or 257/698.ccls.) and (semiconductor or die or chip or ic or (integrated adj circuit))) and (lead or electrode or wire or contact)) and (socket or via or (through adj hole) or slit or slot or opening)) and (insert)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/23 14:58